

Abstract

The present invention relates to a phenol resin mixture obtained by methylene cross-linking reaction of, with phenol, a reaction product which is obtained by halomethylation of biphenyl and contains a side product, an epoxy resin mixture obtained by epoxidation of said phenol resin mixture, and an epoxy resin composition containing said epoxy resin mixture; the epoxy resin mixture of the present invention and the cured product of the epoxy resin composition containing it have not only excellent flame retardancy but also a lower storage elastic modulus at 250°C within a certain range than conventional flame retardant epoxy resin cured products, whereby said epoxy resin mixture or the epoxy resin composition containing it is useful as a semiconductor sealing material where high flame retardancy and excellent lead-free solder durability are required.